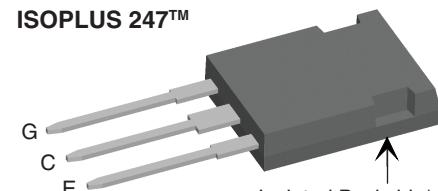
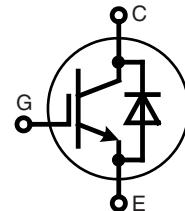


# High Voltage IGBT with optional Diode ISOPLUS™ package

(Electrically Isolated Back Side)

Short Circuit SOA Capability  
Square RBSOA



**E72873**

G = Gate      C = Collector

E = Emitter

Symbol	Conditions	Maximum Ratings		
$V_{CES}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1200	V	
$V_{GCR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GE} = 20 \text{ k}\Omega$	1200	V	
$V_{GES}$	Continuous	$\pm 20$	V	
$V_{GEM}$	Transient	$\pm 30$	V	
$I_{C25}$	$T_c = 25^\circ\text{C}$	50	A	
$I_{C90}$	$T_c = 90^\circ\text{C}$	30	A	
$I_{CM}$	$T_c = 90^\circ\text{C}$ , $t_p = 1 \text{ ms}$	60	A	
<b>RBSOA</b>	$V_{GE} = \pm 15 \text{ V}$ , $T_J = 125^\circ\text{C}$ , $R_G = 47 \Omega$ Clamped inductive load, $L = 30 \text{ mH}$	$I_{CM} = 50$	A	
		$V_{CEK} < V_{CES}$		
$t_{sc}$	$V_{GE} = \pm 15 \text{ V}$ , $V_{CE} = V_{CES}$ , $T_J = 125^\circ\text{C}$	10	$\mu\text{s}$	
<b>(SCSOA)</b>	$R_G = 47 \Omega$ , non repetitive			
$P_c$	$T_c = 25^\circ\text{C}$	IGBT Diode	200 95	W
$T_J$			-55 ... +150	$^\circ\text{C}$
$T_{stg}$			-55 ... +150	$^\circ\text{C}$
$V_{ISOL}$	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	2500	V	
<b>Weight</b>		6	g	

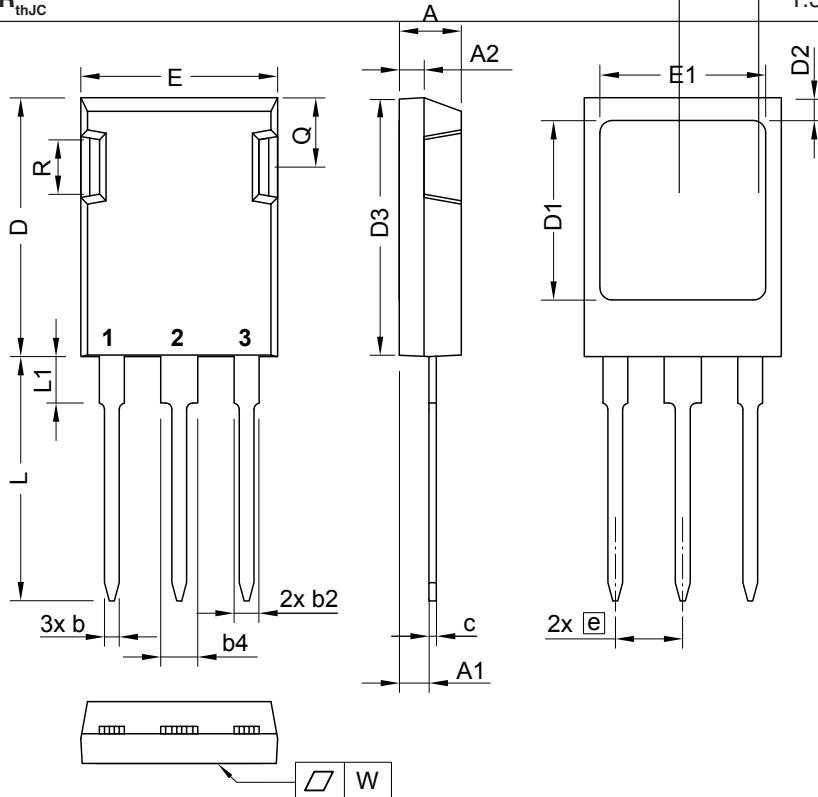
Symbol	Conditions	Characteristic Values		
		( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{(BR)CES}$	$V_{GE} = 0 \text{ V}$	1200		V
$V_{GE(th)}$	$I_c = 1 \text{ mA}$ , $V_{CE} = V_{GE}$	4.5		V
$I_{CES}$	$V_{CE} = V_{CES}$ , $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$		1.5	mA
$I_{GES}$	$V_{CE} = 0 \text{ V}$ , $V_{GE} = \pm 20 \text{ V}$	2.5		mA
$V_{CE(sat)}$	$I_c = 30 \text{ A}$ , $V_{GE} = 15 \text{ V}$	2.4	2.9	V

IXYS reserves the right to change limits, test conditions and dimensions.

20190130a

Symbol	Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{unless otherwise specified})$		
		min.	typ.	max.
$C_{ies}$		1650		pF
$C_{oes}$	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$	250		pF
$C_{res}$		110		pF
$Q_g$	$I_C = 30 \text{ A}, V_{GE} = 15 \text{ V}, V_{CE} = 0.5 V_{CES}$	120		nC
$t_{d(on)}$		100		ns
$t_r$		70		ns
$t_{d(off)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b>	500		ns
$t_f$	$I_C = 30 \text{ A}, V_{GE} = \pm 15 \text{ V}, V_{CE} = 600 \text{ V}, R_G = 47 \Omega$	70		ns
$E_{on}$		4.6		mJ
$E_{off}$		3.4		mJ
$R_{thJC}$			0.6	K/W
$R_{thCH}$	Package with heatsink compound	0.25		K/W

Symbol	Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{unless otherwise specified})$		
		min.	typ.	max.
$V_F$	$I_F = 30 \text{ A}, V_{GE} = 0 \text{ V}$	2.5	2.75	V
$V_F$	$I_F = 30 \text{ A}, V_{GE} = 0 \text{ V}, T_J = 125^\circ\text{C}$	2.0		V
$I_F$	$T_c = 25^\circ\text{C}$		50	A
$I_F$	$T_c = 90^\circ\text{C}$		27	A
$I_{RM}$	$I_F = 30 \text{ A}, -di_F/dt = 400 \text{ A}/\mu\text{s}, V_R = 600 \text{ V}$	20		A
$t_{rr}$	$V_{GE} = 0 \text{ V}, T_J = 125^\circ\text{C}$	200		ns
$t_{rr}$	$I_F = 1 \text{ A}, -di_F/dt = 100 \text{ A}/\mu\text{s}, V_R = 30 \text{ V}, V_{GE} = 0 \text{ V}$	40		ns
$R_{thJC}$			1.3	K/W



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.91	2.16	0.075	0.085
b	1.14	1.40	0.045	0.055
b2	1.91	2.20	0.075	0.087
b4	2.92	3.24	0.115	0.128
c	0.61	0.83	0.024	0.033
D	20.80	21.34	0.819	0.840
D1	15.75	16.26	0.620	0.640
D2	1.65	2.15	0.065	0.085
D3	20.30	20.70	0.799	0.815
E	15.75	16.13	0.620	0.635
E1	13.21	13.72	0.520	0.540
e	5.45	BSC	0.215	BSC
L	19.81	20.60	0.780	0.811
L1	3.81	4.38	0.150	0.172
Q	5.59	6.20	0.220	0.244
R	4.25	5.50	0.167	0.217
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.04 mm über der Kunststoffoberfläche der Bauteilunterseite  
 The convex bow of substrate is typ. < 0.04 mm over plastic surface level of device bottom side

Die Gehäuseabmessungen entsprechen dem Typ TO-247 AD gemäß JEDEC außer Schraubloch und  $L_{max}$ .  
 This drawing will meet all dimensions requirement of JEDEC outline TO-247 AD except screw hole and except  $L_{max}$ .

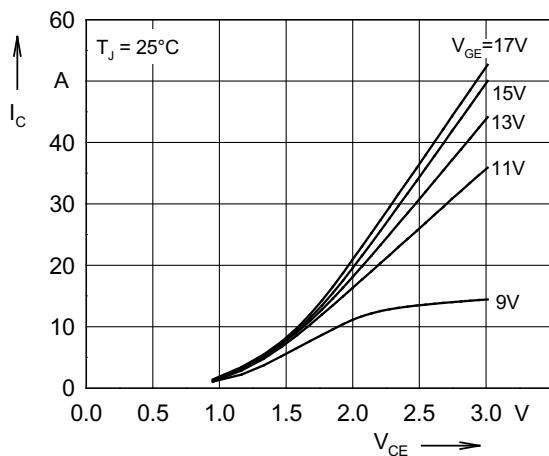


Fig. 1 Typ. output characteristics

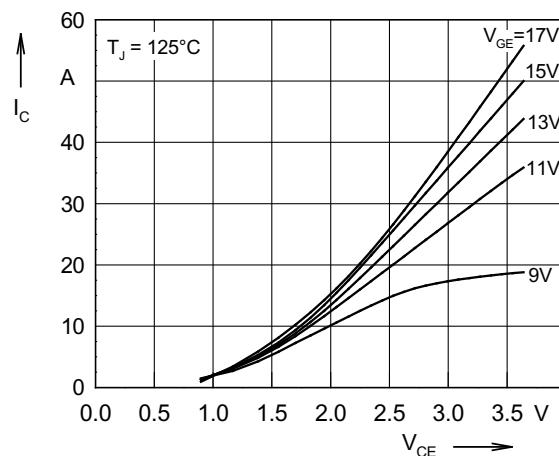


Fig. 2 Typ. output characteristics

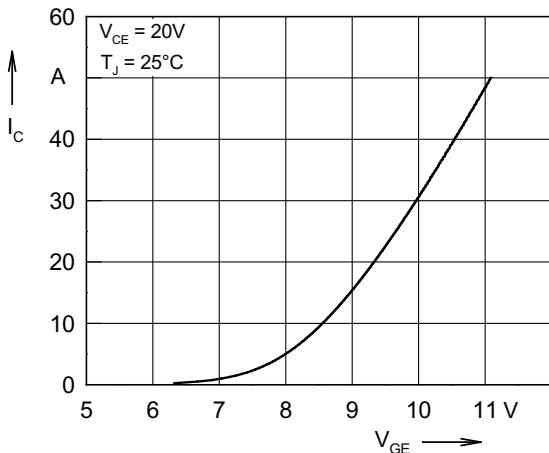


Fig. 3 Typ. transfer characteristics

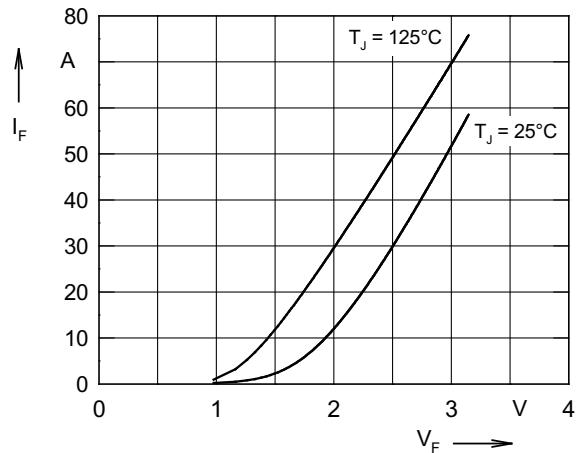


Fig. 4 Typ. forward characteristics of free wheeling diode

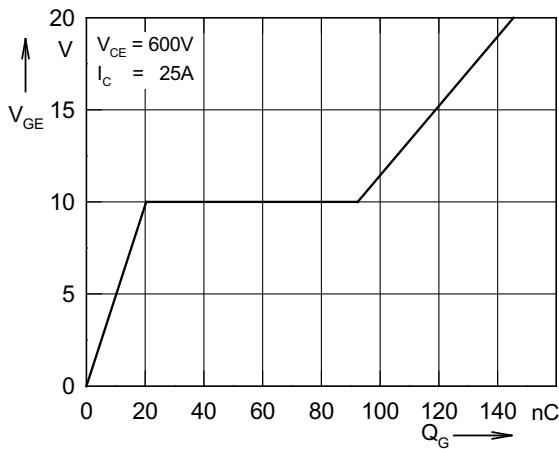


Fig. 5 Typ. turn on gate charge

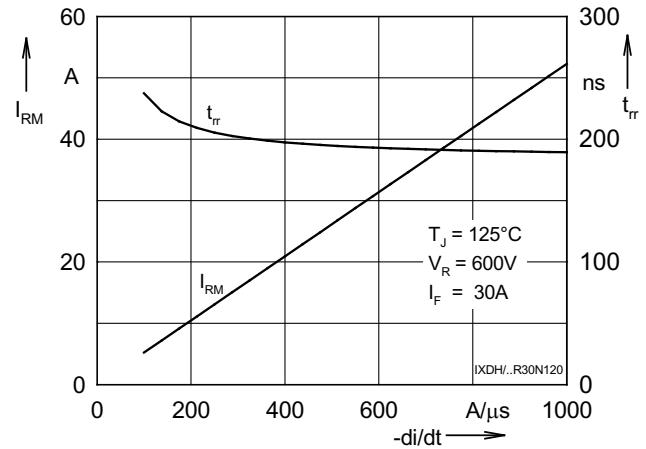


Fig. 6 Typ. turn off characteristics of free wheeling diode

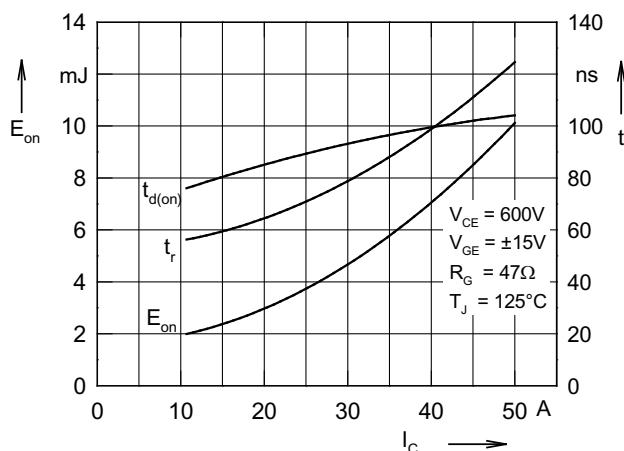


Fig. 7 Typ. turn on energy and switching times versus collector current

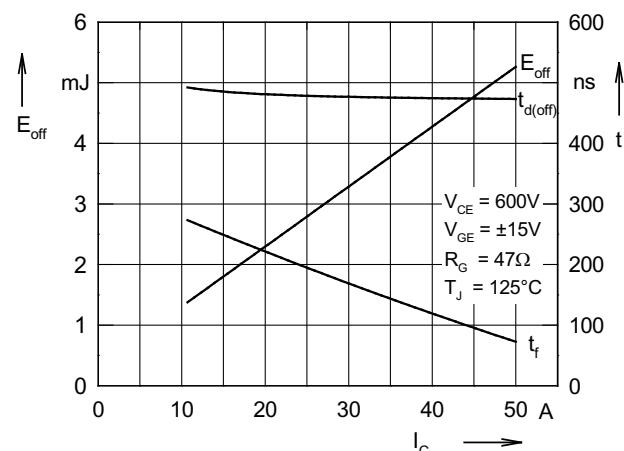


Fig. 8 Typ. turn off energy and switching times versus collector current

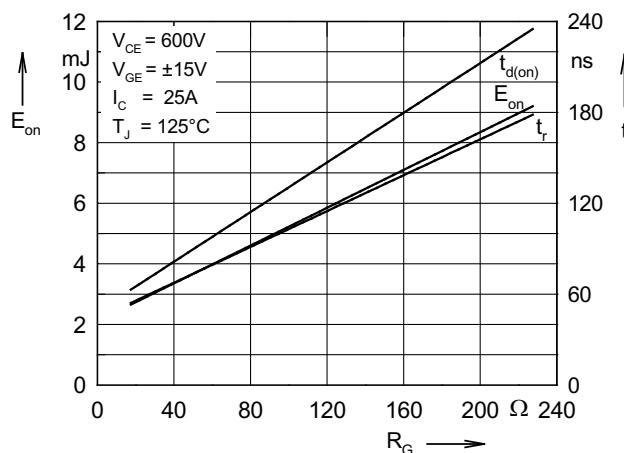


Fig. 9 Typ. turn on energy and switching times versus gate resistor

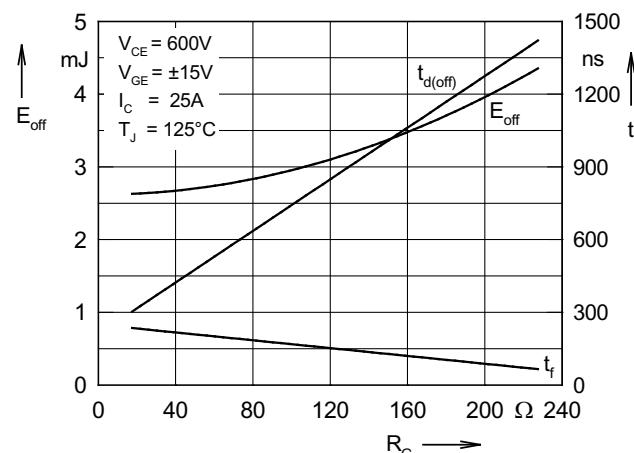


Fig.10 Typ. turn off energy and switching times versus gate resistor

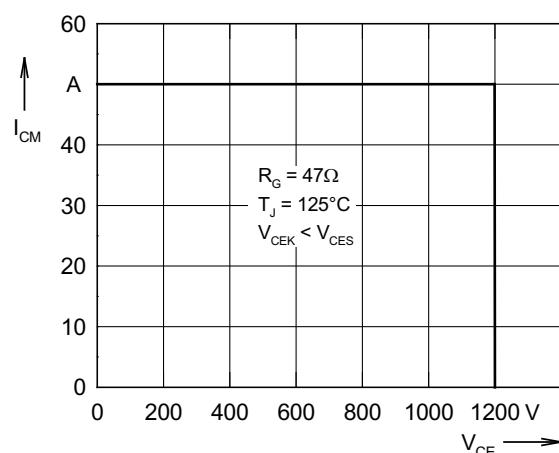


Fig. 11 Reverse biased safe operating area RBSOA

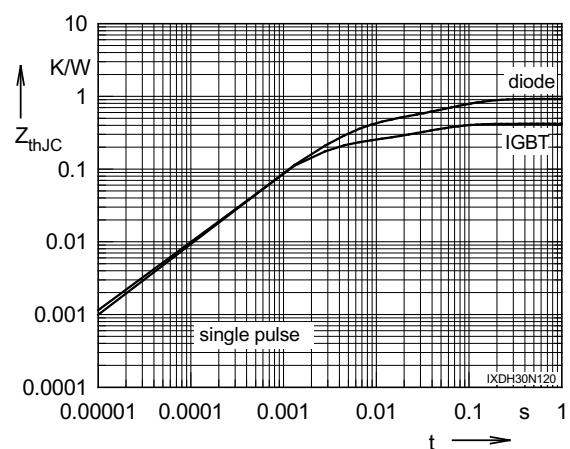


Fig. 12 Typ. transient thermal impedance

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